

EAST - [10612744.wsp:1]

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 (1276) microelectronic near packag\$3
 (168) (microelectronic near packag\$3) and
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DBs: USPAT, EPO, JPO, DERWENT, IBM, TDB ☐ Plurals

Default operator: OR ☒ Highlight all hit terms initially

(microelectronic near packag\$3) and core

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
66	<input type="checkbox"/>	<input type="checkbox"/>	US 6202298 B1	20010320	32	Microelectronic connections with liquid conductive elements	29/840	257/E21.503; 257/E23.021;
67	<input type="checkbox"/>	<input type="checkbox"/>	US 6190509 B1	20010220	22	Methods of making anisotropic conductive elements for use in microelectronic	204/164	257/E21.514; 257/E23.067;
68	<input type="checkbox"/>	<input type="checkbox"/>	US 6162661 A	20001219	29	Spacer plate solder ball placement fixture and methods therefor	438/108	257/E21.508; 438/613;
69	<input type="checkbox"/>	<input type="checkbox"/>	US 6121340 A	20000919	39	Photodefinable dielectric compositions comprising polycyclic polymers	522/31	430/270.1; 430/286.1;
70	<input type="checkbox"/>	<input type="checkbox"/>	US 6121069 A	20000919	12	Interconnect structure for joining a chip to a circuit card	438/106	257/E21.511; 257/E23.021;
71	<input type="checkbox"/>	<input type="checkbox"/>	US 6119927 A	20000919	20	Method and apparatus for placing and attaching solder balls to substrates	228/254	228/202; 228/219;
72	<input type="checkbox"/>	<input type="checkbox"/>	US 6117694 A	20000912	24	Flexible lead structures and methods of making same	438/14	438/118; 438/127;
73	<input type="checkbox"/>	<input type="checkbox"/>	US 6114048 A	20000905	13	Functionally graded metal substrates and process for making same	428/547	228/246; 257/720;
74	<input type="checkbox"/>	<input type="checkbox"/>	US 6097857 A	20000801	14	Microelectronic module having optical and electrical interconnects	385/14	
75	<input type="checkbox"/>	<input type="checkbox"/>	US 6096111 A	20000801	7	Exothermically sintered homogeneous composite and fabrication method	75/228	257/E23.112; 419/12;
76	<input type="checkbox"/>	<input type="checkbox"/>	US 6086386 A	20000711	26	Flexible connectors for microelectronic elements	439/70	228/180.1; 29/843;